(12) INTERNATIONAL APPLICATION PUBLISHED UNDER THE PATENT COOPERATION TREATY (PCT)

(19) World Intellectual Property Organization International Bureau





(43) International Publication Date 28 April 2005 (28.04.2005)

PCT

(10) International Publication Number WO 2005/038903 A1

(51) International Patent Classification7: H01L 21/762, 21/304

(21) International Application Number:

PCT/EP2004/052548

- (22) International Filing Date: 14 October 2004 (14.10.2004)
- (25) Filing Language:

English

(26) Publication Language:

English

(30) Priority Data: 03/50674

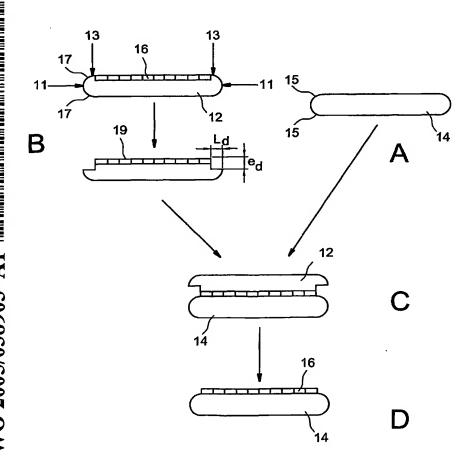
- 14 October 2003 (14.10.2003) FR 60/568,700 7 May 2004 (07.05.2004) US
- (71) Applicant (for all designated States except US): TRACIT TECHNOLOGIES; Centr'Alp, 52 rue de Corporat, F-38430 MOIRANS (FR).
- (72) Inventors; and
- (75) Inventors/Applicants (for US only): ASPAR, Bernard

[FR/FR]; 110 Lotissement le Hameau des Ayes, F-38140 Rives (FR). LAGAHE-BLANCHARD, Chrystelle [FR/FR]; Route de la Cascade, F-38134 Saint Joseph De Rivière (FR).

- (74) Agent: POULIN, Gérard; BREVALEX, 3, rue du Docteur Lancereaux, F-75008 PARIS (FR).
- (81) Designated States (unless otherwise indicated, for every kind of national protection available): AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BW, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, EG, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NA, NI, NO, NZ, OM, PG, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, SY, TJ, TM, TN, TR, TT, TZ, UA, UG, US, UZ, VC, VN, YU, ZA, ZM, ZW.
- (84) Designated States (unless otherwise indicated, for every kind of regional protection available): ARIPO (BW, GH,

[Continued on next page]

(54) Title: METHOD FOR PREPARING AND ASSEMBLING SUBSTRATES



(57) Abstract: The invention relates to a method for assembling a first and a second wafer (12 and 14) of material, comprising: - a routing stage of at least the first wafer (12); - an assembling stage of the first and the second wafer.



GM, KE, LS, MW, MZ, NA, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PL, PT, RO, SE, SI, SK, TR), OAPI (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG).

Published:

with international search report

before the expiration of the time limit for amending the claims and to be republished in the event of receipt of amendments

For two-letter codes and other abbreviations, refer to the "Guidance Notes on Codes and Abbreviations" appearing at the beginning of each regular issue of the PCT Gazette.